

wherein said circuit board includes at least two grooves defined by said conductive pattern and located approximate to one of said bonding areas to put the bonding area therebetween, and wherein at least one of said grooves does not electrically isolate said conductive pattern.

22. (Once Amended) A chip part device comprising:

a circuit board including a board main body and a conductive layer formed on said board main body, said conductive layer having a plurality of bonding areas defined by a conductive pattern; and

a chip element mounted on said circuit board, and having a plurality of bump electrodes which are simultaneously joined with said bonding areas by ultrasonic bonding,

wherein said circuit board includes means for evenly distributing ultrasonic energy applied in a vibrating direction to said plurality of bump electrodes and said plurality of bonding areas.

REMARKS

Favorable reconsideration of this application as presently amended is respectfully requested.

Claims 16-26 are presently active in this case, Claims 19 and 22 having been amended by way of this Amendment. Claims 16-18 have been allowed.

Claims 22-26 were rejected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventors, at the time the application was filed, had possession of the claimed invention. The Applicants respectfully traverse this rejection.